TOSHIBA Transistor Silicon NPN Epitaxial Planar Type

MT6L52AE

VHF~UHF Band Low Noise Amplifier Applications

- Two devices are built in to the super-thin and extreme super mini (6 pins) package: ES6

Mounted Devices

	Q1: SSM (TESM)	Q2: SSM (TESM)
Three-pins (SSM/TESM) mold products are corresponded.	MT3S03AS (MT3S03AT)	MT3S04AS (MT3S04AT)

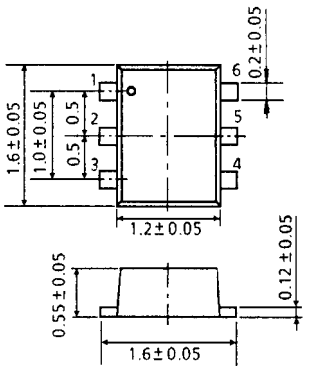
Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Q1	Q2	Unit
Collector-base voltage	V_{CBO}	10	10	V
Collector-emitter voltage	V_{CEO}	5	5	V
Emitter-base voltage	V_{EBO}	2	2	V
Collector current	I_C	40	40	mA
Base current	I_B	10	10	mA
Collector power dissipation	P_C (Note 1)	100		mW
Junction temperature	T_j	125		°C
Storage temperature range	T_{stg}	−55~125		°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Total power dissipation of Q1 and Q2.

Unit: mm

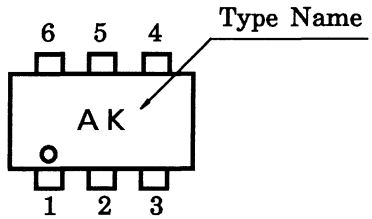


1. COLLECTOR 1
2. EMITTER 1
3. COLLECTOR 2
4. BASE 2
5. EMITTER 2
6. BASE 1

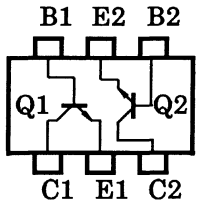
JEDEC	—
JEITA	—
TOSHIBA	2-2N1C

Weight: 0.003 g (typ.)

Marking



Pin Assignment (top view)



Electrical Characteristics Q1 (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Collector cut-off current	I_{CBO}	V_{CB} = 5 V, I_E = 0	—	—	0.1	μA
Emitter cut-off current	I_{EBO}	V_{EB} = 1 V, I_C = 0	—	—	1	μA
DC current gain	h_{FE}	V_{CE} = 1 V, I_C = 5 mA	80	—	160	
Transition frequency	f_T (1)	V_{CE} = 1 V, I_C = 5 mA	5	7	—	GHz
	f_T (2)	V_{CE} = 3 V, I_C = 10 mA	7	10	—	
Insertion gain	$\|S_{21e}\|^2$ (1)	V_{CE} = 1 V, I_C = 5 mA, f = 2 GHz	—	5	—	dB
	$\|S_{21e}\|^2$ (2)	V_{CE} = 3 V, I_C = 20 mA, f = 2 GHz	3	6.5	—	
Noise figure	NF (1)	V_{CE} = 1 V, I_C = 5 mA, f = 2 GHz	—	1.7	3	dB
	NF (2)	V_{CE} = 3 V, I_C = 7 mA, f = 2 GHz	—	1.4	2.2	
Reverse transfer capacitance	C_{re}	V_{CB} = 1 V, I_E = 0, f = 1 MHz (Note 2)	—	0.8	1.15	pF

Note 2: C_{re} is measured by 3 terminal method with capacitance bridge.

Electrical Characteristics Q2 (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Collector cut-off current	I_{CBO}	V_{CB} = 5 V, I_E = 0	—	—	0.1	μA
Emitter cut-off current	I_{EBO}	V_{EB} = 1 V, I_C = 0	—	—	1	μA
DC current gain	h_{FE}	V_{CE} = 1 V, I_C = 5 mA	80	—	160	
Transition frequency	f_T (1)	V_{CE} = 1 V, I_C = 5 mA	2	4.5	—	GHz
	f_T (2)	V_{CE} = 3 V, I_C = 7 mA	5	7	—	
Insertion gain	$\|S_{21e}\|^2$ (1)	V_{CE} = 1 V, I_C = 5 mA, f = 1 GHz	—	8.5	—	dB
	$\|S_{21e}\|^2$ (2)	V_{CE} = 3 V, I_C = 20 mA, f = 1 GHz	7.5	11	—	
Noise figure	NF (1)	V_{CE} = 1 V, I_C = 5 mA, f = 1 GHz	—	1.3	2.2	dB
	NF (2)	V_{CE} = 3 V, I_C = 7 mA, f = 1 GHz	—	1.2	2	
Reverse transfer capacitance	C_{re}	V_{CB} = 1 V, I_E = 0, f = 1 MHz (Note 2)	—	0.9	1.25	pF

Note 2: C_{re} is measured by 3 terminal method with capacitance bridge.

Handling Precaution

When handling individual devices (which are not yet mounted on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

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